




<b>PCN Number:</b>	20140930003B	<b>PCN Date:</b>	05/06/2016				
<b>Title:</b>	Qualification of Amkor Philippines as an Additional Assembly and Test location for Select Devices in the SOIC package						
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services				
<b>Proposed 1<sup>st</sup> Ship Date:</b>	03/04/2015	<b>Estimated Sample Availability:</b>	Date provided upon request				
<b>Change Type:</b>							
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process				
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification				
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling				
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material				
<input type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials				
<input type="checkbox"/>		<input type="checkbox"/>	Part number change				
<b>PCN Details</b>							
<b>Description of Change:</b>							
<p><b>Revision B</b> is to announce the <u>retraction</u> of select devices. These devices will continue to be manufactured as prior and will not be subjected to the change described in this notification. Affected devices are identified with a <del>strikethrough</del> and are highlighted in yellow in the Product Affected Section.</p> <p>Texas Instruments is pleased to announce the qualification of Amkor Philippines as an additional Assembly and Test location for the devices listed below. Assembly material differences are noted below:</p>							
	<b>ASEH</b>	<b>Amkor Philippines</b>					
<b>Mount Compound</b>	SID#EY1000063	<b>SID#101374994</b>					
<b>Mold Compound</b>	SID#EN2000509	<b>SID#101379294</b>					
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.							
<b>Reason for Change:</b>							
Continuity of Supply							
<b>Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):</b>							
None							
<b>Changes to product identification resulting from this PCN:</b>							
<i>Assembly Site</i>							
ASE Shanghai	Assembly Site Origin (22L)	ASO: ASH					
<b>AMKOR (AP1)</b>	<b>Assembly Site Origin (22L)</b>	<b>ASO: AKR</b>					
Sample product shipping label (not actual product label)							
 <p>MADE IN: Malaysia 2DC: 20</p> <table border="1"> <tr> <td>MSL 2 /260C/1 YEAR</td> <td>SEAL DT</td> </tr> <tr> <td>MSL 1 /235C/UNLIM</td> <td>03/29/04</td> </tr> </table> <p>OPT: ITEM: 39 <b>LBL: 5A (L)T0:1750</b></p>	MSL 2 /260C/1 YEAR	SEAL DT	MSL 1 /235C/UNLIM	03/29/04			<p>(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO: USA (22L) ASO: MLA (23L) ACO: MYS</p>
MSL 2 /260C/1 YEAR	SEAL DT						
MSL 1 /235C/UNLIM	03/29/04						

**Topside Device marking:**

Assembly site code for ASH= A

Assembly site code for AKR= 4

**Product Affected**

905X5433200	TPS54228DDAR	<b>TPS54332DDA</b>	TPS54527DDAR
HPA01123DDAR	TPS54229DDA	<b>TPS54332DDAR</b>	TPS54528DDA
SN1101004DDAR	TPS54229DDAR	<b>TPS54335DDA</b>	TPS54528DDAR
SN1101005DDAR	TPS54229EDDA	<b>TPS54335DDAR</b>	TPS54627DDA
SN1106041DDAR	TPS54229EDDAR	TPS54427DDA	TPS54627DDAR
SN1110024DDAR	<b>TPS5432DDA</b>	TPS54427DDAR	TPS54628DDA
SN1208017DDAR	<b>TPS5432DDAR</b>	TPS54428DDA	TPS54628DDAR
SN54229EDDAR	<b>TPS54332CDDA</b>	TPS54428DDAR	TPS56628DDA
TPS54228DDA	<b>TPS54332CDDAR</b>	TPS54527DDA	TPS56628DDAR

**Qualification Report**

Amkor: Qualify Amkor Assembly (AP1) with 101379294 mold compound, 101374994 mount compound + Cu wire (2.0 MIL) on PWR DCS SOIC devices with BOAC

Approval 09/18/2014

**Product Attributes**

Attributes	Qual Device: TPS54327DDA	Qual Device: TPS54627DDA
<b>Assembly Site</b>	AMKOR AP1	AMKOR AP1
<b>Package Family</b>	SOIC	SOIC
<b>Flammability Rating</b>	UL 94 V-0	UL 94 V-0
<b>Wafer Fab Site</b>	RFAB	RFAB
<b>Wafer Fab Process</b>	LBC7	LBC7

- QBS: Qual By Similarity

- Qual Devices qualified at LEVEL2-260C: TPS54327DDA, TPS54627DDA

## Qualification Results

*Data Displayed as: Number of lots / Total sample size / Total failed*

Type	Test Name / Condition	Duration	Qual Device: TPS54327DDA	Qual Device: TPS54627DDA
THB	Biased Temperature and Humidity, 85C/85%RH	1000 Hours	3/231/0	-
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0
TC-BP	Auto Post Temp. Cycle Bond Pull	per MIL-STD 883 Method 2011	3/15/0	3/15/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0
HTSL	High Temp Storage Bake 170C	420 Hours	3/229/0	-
ED	Electrical Characterization.	Per Datasheet Parameters	1/30/0	-
FLAM	Flammability (UL 94V-0)	--	3/15/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	<a href="mailto:PCNAmericasContact@list.ti.com">PCNAmericasContact@list.ti.com</a>
Europe	<a href="mailto:PCNEuropeContact@list.ti.com">PCNEuropeContact@list.ti.com</a>
Asia Pacific	<a href="mailto:PCNAsiaContact@list.ti.com">PCNAsiaContact@list.ti.com</a>
Japan	<a href="mailto:PCNJapanContact@list.ti.com">PCNJapanContact@list.ti.com</a>